



500.37328CX1

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): YOKOGAWA, et al
Serial No.: 09/336,687
Filed: June 21, 1999
For: PLASMA PROCESSING SYSTEM AND METHOD
Group: 1763
Examiner: L. Alejandro

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MLW

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AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

July 1, 2002

Sir:

The following amendments and remarks are respectfully submitted in connection with the above-identified application in response to the Office Action dated January 30, 2002.

IN THE CLAIMS:

Please amend the claims 2-12, 14-33 and 36-54 as follows:

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2. (twice amended) A plasma etching system in accordance with claim 1, wherein the planar plate has a diameter ranging from 0.7 times that of the sample to 1.2 times that of the sample.

3. (twice amended) A plasma etching system in accordance with claim 1, wherein the electromagnetic wave to generate plasma has a frequency ranging from 300 MHz to 500 MHz.

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